

## CLAIMS

1. A method of making a chip resistor comprising the steps of:

preparing an aggregate board which includes a first region  
5 and a second region which are spaced from each other via an  
excess portion;

forming a conductor pattern extending to bridge the first  
region and the second region;

forming a resistor element in each of the first region and  
10 the second region for connection to the conductor pattern; and

cutting the aggregate board at the excess portion;

the conductor pattern including a thinner-walled portion  
extending across the excess portion and a thicker-walled  
portion connected to the thinner-walled portion and spaced from  
15 the excess portion.

2. The method according to claim 1, wherein the thinner-walled  
portion has a thickness of 0.1-3.0 $\mu$ m.

20 3. The method according to claim 1, wherein the thicker-walled  
portion has a thickness of 5-25 $\mu$ m.

4. The method according to claim 1, wherein the conductor  
pattern forming step includes a sub-step of applying a  
25 conductor paste for the thicker-walled portion and a sub-step  
of applying a conductor paste for the thinner-walled portion.

5. The method according to claim 4, wherein the conductor paste for the thicker-walled portion and the conductor paste for the thinner-walled portion are baked simultaneously.

5 6. The method according to claim 4, wherein the conductor paste for the thicker-walled portion and the conductor paste for the thinner-walled portion are made of a same material.

7. The method according to claim 1, further comprising the step  
10 of forming a resistance adjusting groove in the resistor element.

8. A chip resistor comprising:

an insulating substrate having an upper surface and a side  
15 surface;

a first conductor pattern formed on the upper surface; and  
a resistor element connected to the first conductor  
pattern;

the first conductor pattern including a thinner-walled  
20 portion contacting the upper surface, and a thicker-walled  
portion connected to the thinner-walled portion and contacting  
the upper surface, the thinner-walled portion being spaced from  
the resistor element and extending up to the side surface, the  
thicker-walled portion contacting the resistor element and  
25 being spaced from the side surface.

9. The resistor according to claim 8, further comprising a second conductor pattern extending on the first conductor pattern, the second conductor pattern contacting both of the thinner-walled portion and the thicker-walled portion.

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10. The resistor according to claim 8, wherein the thinner-walled portion has a thickness of 0.1-3.0 $\mu$ m, whereas the thicker-walled portion has a thickness of 5-25 $\mu$ m.